

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

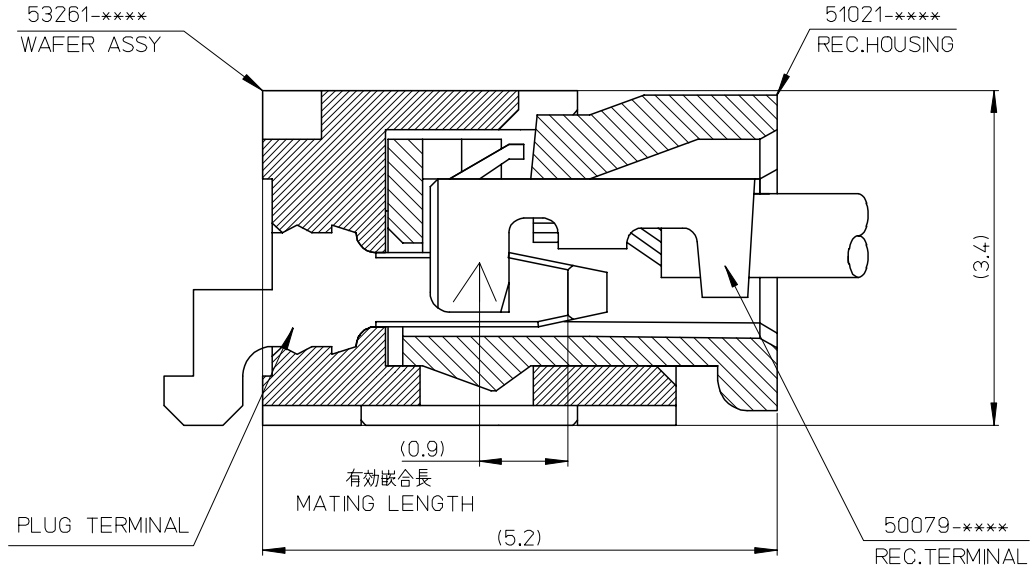
C

B

B

A

A

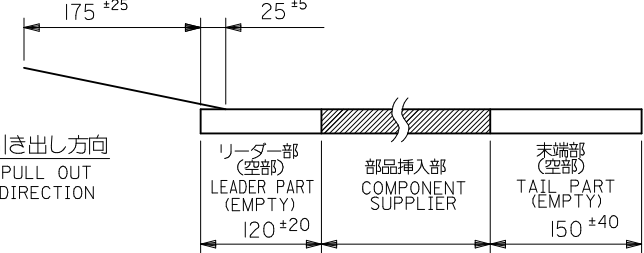


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記  
NOTES

- 53261-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART  
トップテープ未接着部 TOP TAPE NON-BONDED PART



- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

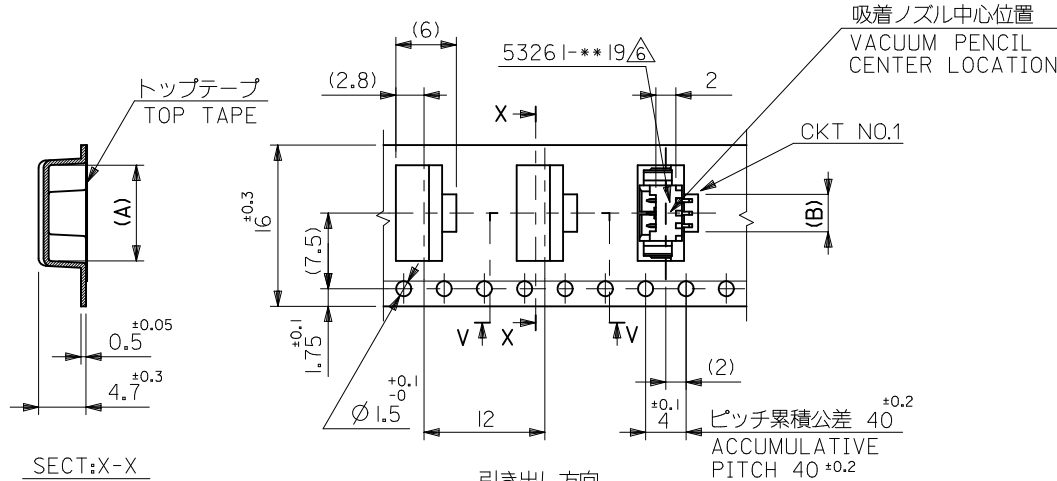
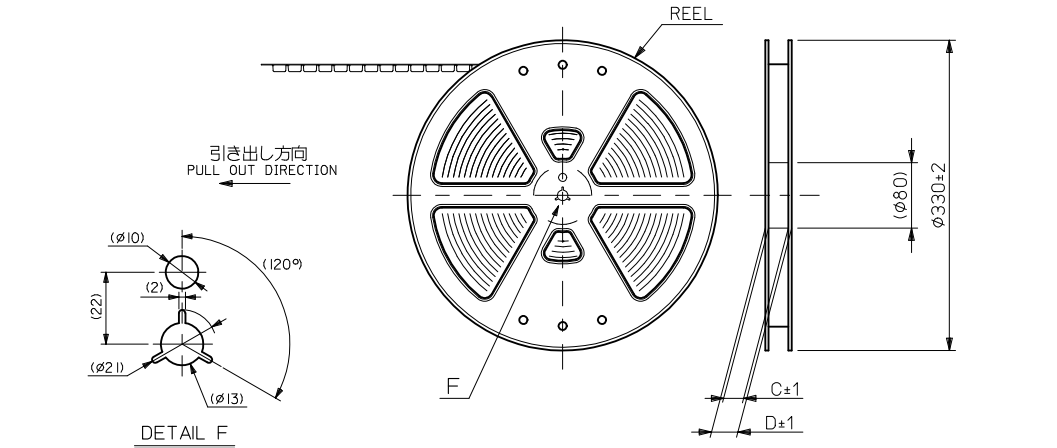
- 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90

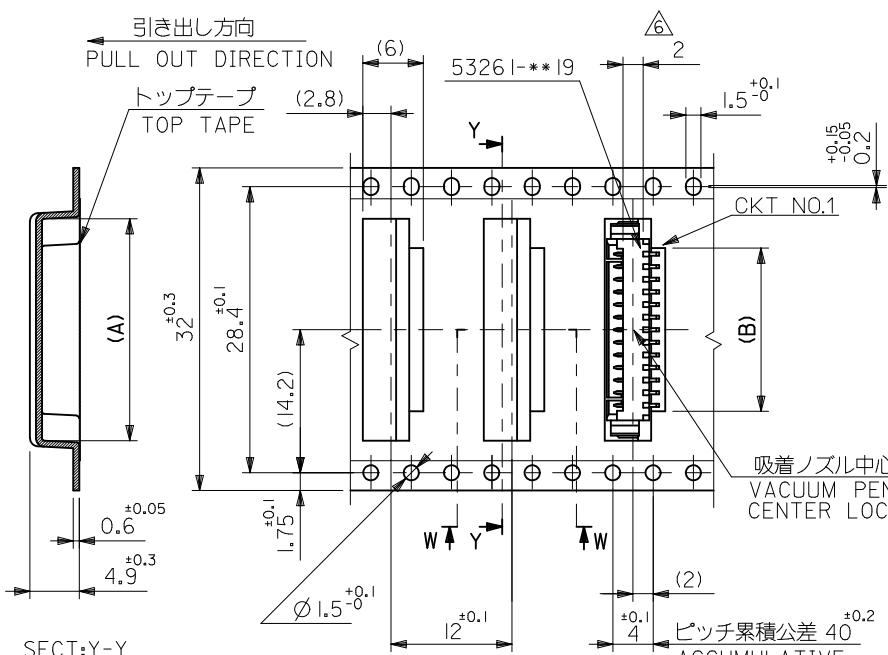
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

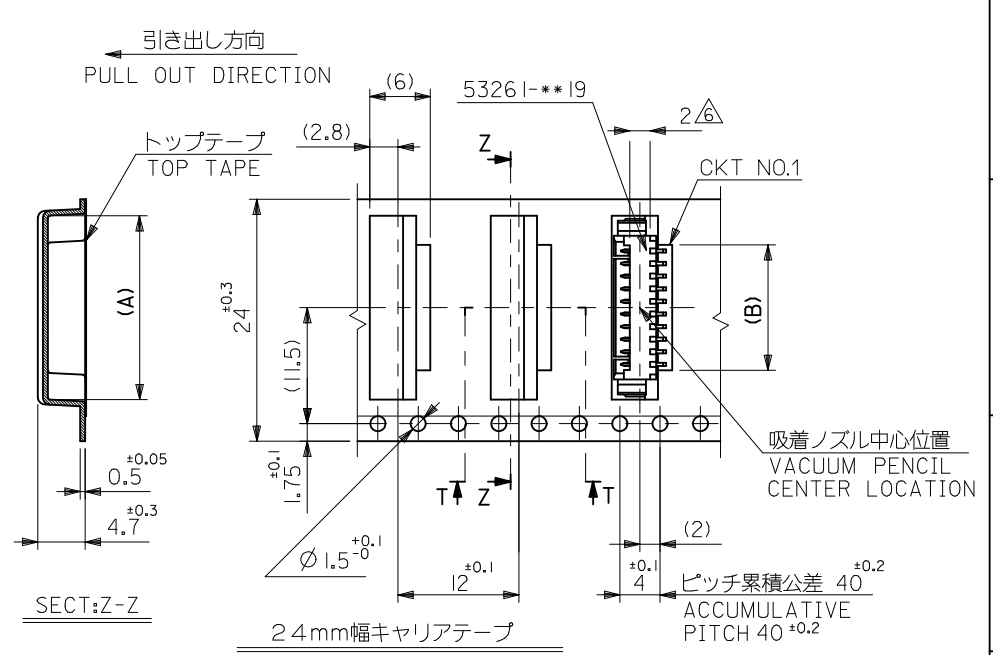
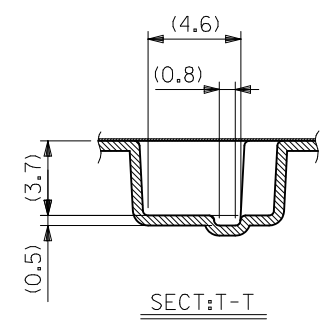
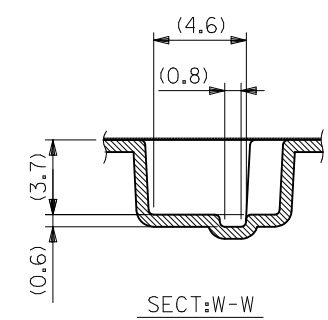
16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: H. SHIMABUKUR DATE: '04/02/06 CHECKED BY: K. TOJO DATE: '04/02/06 APPROVED BY: NUKITA DATE: 2010/02/18	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	MATERIAL NO. SEE TABLE & SHEET 2,3	DOCUMENT NO. SD-53261-023
REV	REV	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			





32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

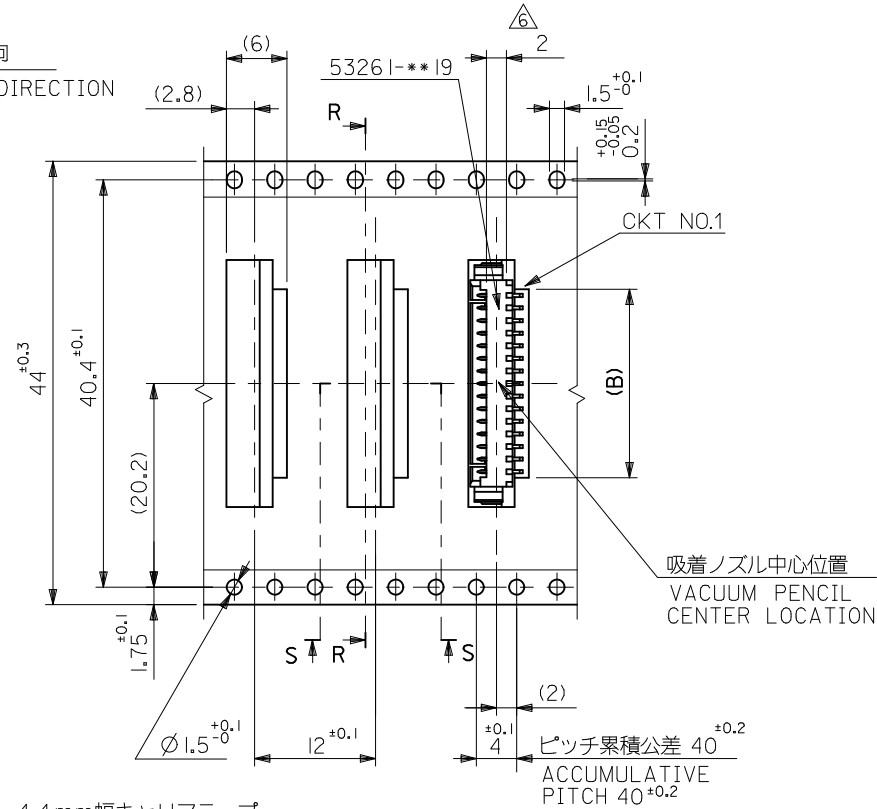
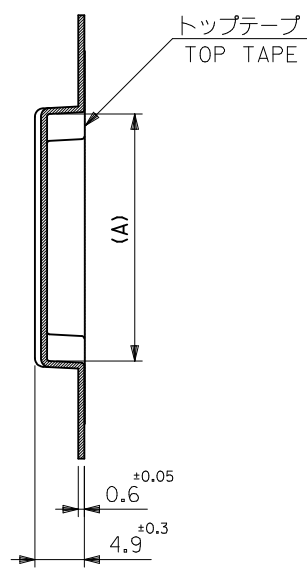


24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

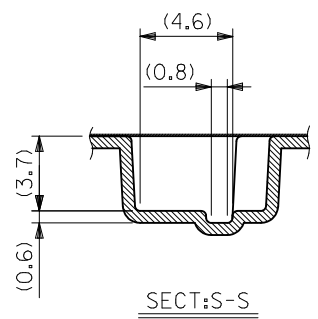
32	37.4	33.4	16.2	22	53261-1371	13		
			14.95	20.75	-1271	12		
24	29.4	25.4	13.7	19.5	-1171	11		
			12.45	18.25	-1071	10		
			11.2	17	-0971	9		
			9.95	15.75	-0871	8		
			8.7	14.5	-0771	7		
			7.45	13.25	-0671	6		
			6.2	12	-0571	5		
			4.95	10.75	53261-0471	4		
キャリアテープ幅 CARRIER TAPE WIDTH			D	C	B	A	EMBOSSD TAPE PACKAGE 極数 CTKT.	
MODEL NO. 53261-***71			DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC	THIRD ANGLE PROJECTION

REVISED EC NO: D DRWN:YGOITO CHKD:KASAKAWA APPR:	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRAWN BY H. SHIMABUKUR		DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
	10 UNDER	±0.2	CHECKED BY K. TOJO		DATE '04/02/06		
	10 OVER 30 UNDER	±0.25	APPROVED BY NUKITA		DATE 2010/02/18		
	30 OVER	±0.3	MATERIAL NO. SEE TABLE & SHEET 13		DOCUMENT NO. SD-53261-023		
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 2 OF 3		

引き出し方向  
PULL OUT DIRECTION

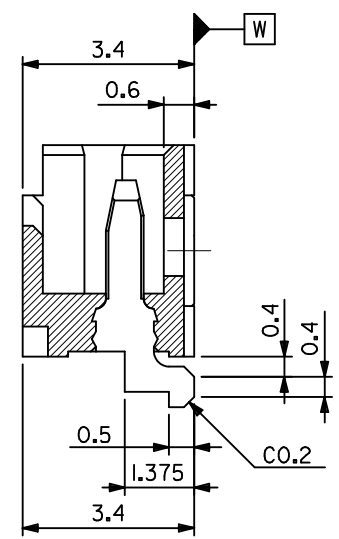
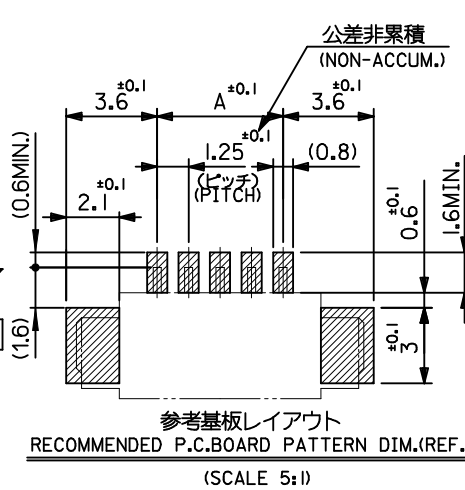
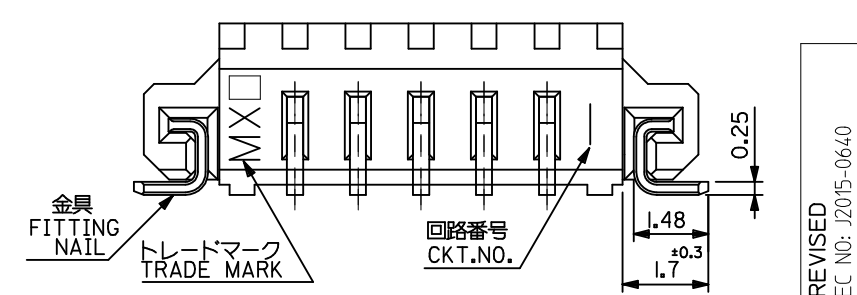
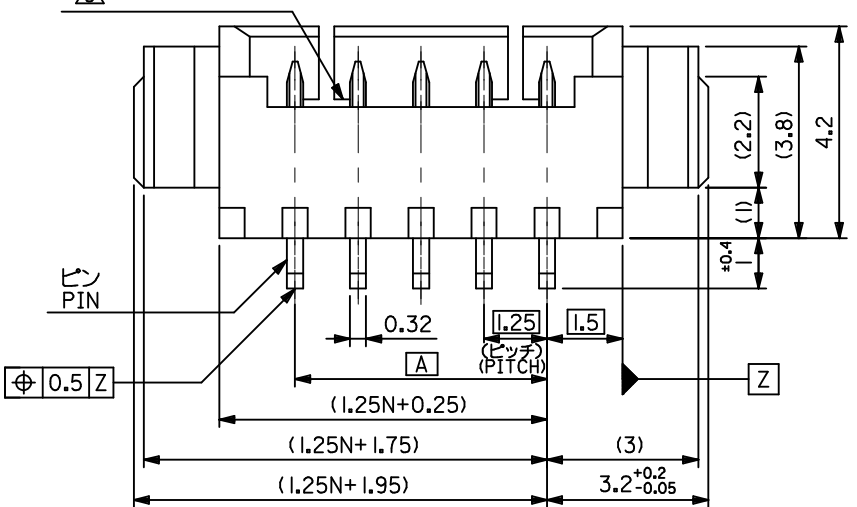
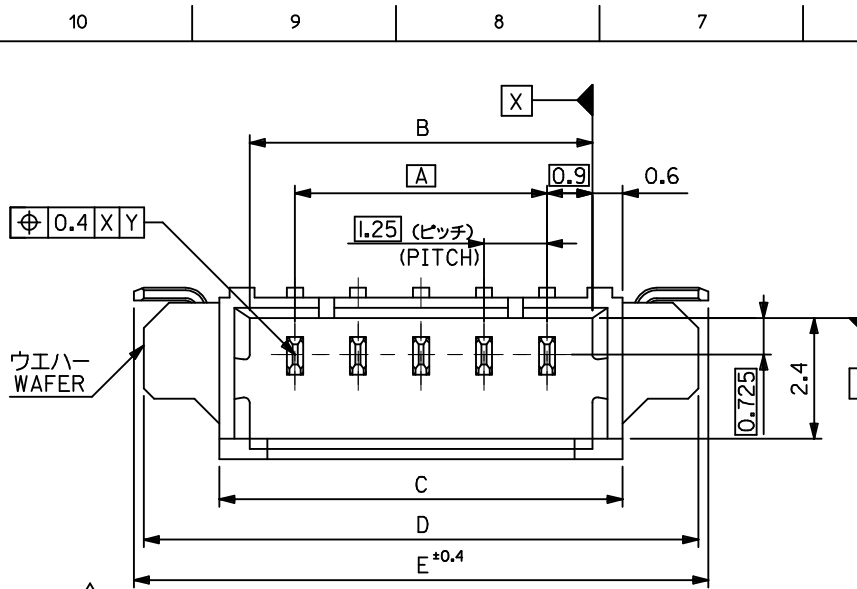


44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



44	49.4	45.4	18.7	24.5	53261-1571	15
			17.45	23.25	53261-1471	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17	10 UNDER ±0.2	MM ONLY	---	METRIC	☉ □
DRWN: YGOTO		10 OVER 30 UNDER ±0.25	DRAWN BY DATE			TITLE
CHKD: KASAKAWA		30 OVER ±0.3	H. SHIMABUKUR '04/02/06			1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
APPR:		ANGULAR ±3 °	CHECKED BY DATE			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	K. TOJO '04/02/06			
			APPROVED BY DATE			
			NUKITA 2010/02/18			
			MATERIAL NO.			
			SEE TABLE & SHEET 12			
			SIZE A3			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
					MOLEX MOLEX INCORPORATED	
					DOCUMENT NO. SD-53261-023	SHEET NO. 3 OF 3



注記 NOTES

- 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
- 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
PIN: PHOS-BRO  
銅メッキ: 1.0 マイクロメートル以上  
TIN: 1.0 MICROMETER MINIMUM  
ニッケル下地: 1.0 マイクロメートル以上  
NICKEL(UNDER PLATING): 1.0 MICROMETER MINIMUM  
金具: リン青銅  
FITTING NAIL: PHOS-BRO  
銅メッキ: 1.0 マイクロメートル以上  
TIN: 1.0 MICROMETER MINIMUM  
ニッケル下地: 1.0 マイクロメートル以上  
NICKEL(UNDER PLATING): 1.0 MICROMETER MINIMUM
- ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
- ソルダーテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05 MAX., 下方向に 0.1 MAX. とする。 [W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05 MAX.  
LOWER SIDE: 0.1 MAX.
- 本製品は 53261-\*\*-\*\*10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-\*\*10
- ELV 及び RoHS 適合品  
ELV AND RoHS COMPLIANT.

26.4	26	23	21.8	20	53261-1771	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1571	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1471	-1419	14	
21.4	21	18	16.8	15	-1371	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1271	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1171	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1071	-1019	10	
16.4	16	13	11.8	10	-0971	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0871	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0771	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0671	-0619	6	
11.4	11	8	6.8	5	-0571	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0471	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0371	-0319	3	
53261-**-**19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2

REVISED EC NO: J2015-0640 2014/11/12  
DRWN: YAKE 2014/11/12  
CHKD: KASAKAWA 2014/11/12  
APPR: NUKITA 2014/11/17

GENERAL TOLERANCES (UNLESS SPECIFIED)  
10 UNDER ±0.2  
10 OVER 30 UNDER ±0.25  
30 OVER ±0.3  
ANGULAR ±3 °  
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY  
SCALE: 10:1  
DESIGN UNITS: METRIC  
THIRD ANGLE PROJECTION

DRAWN BY: HSHIMABU DATE: 04/02/06  
CHECKED BY: KTOJO DATE: 04/02/06  
APPROVED BY: MSASAO DATE: 04/02/06

MATERIAL NO. SEE DRAWING  
DOCUMENT NO. SD-53261-024  
SHEET NO. 1 OF 1

1.25 WIRE TO BOARD WAFER ASS FOR SMT

**molex**

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